

MA27077G

Silicon epitaxial planar type

For band switching

■ Features

- Low forward dynamic resistance r_f
- Less voltage dependence of diode capacitance C_D
- SSS-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

■ Package

- Code
SSSMini2-F3
- Pin Name
1: Anode
2: Cathode

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	35	V
Forward current	I_F	100	mA
Operating ambient temperature *	T_{opr}	-25 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

■ Marking Symbol: C

Note) *: Maximum ambient temperature during operation.

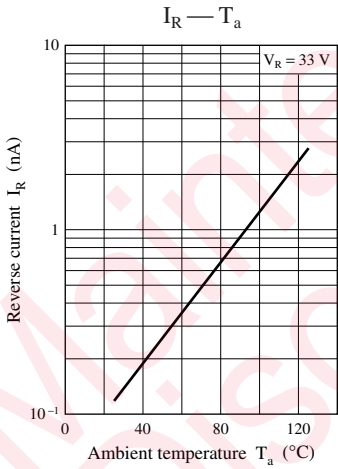
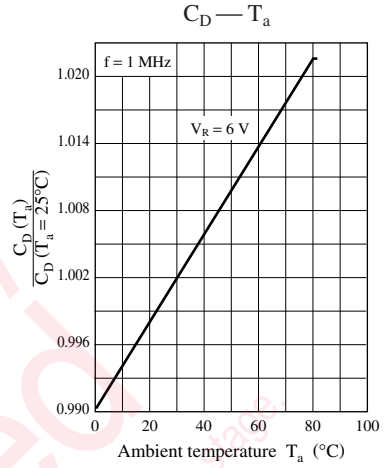
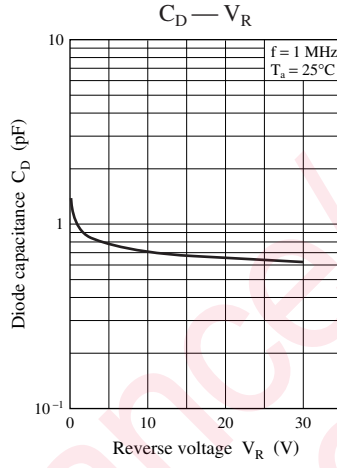
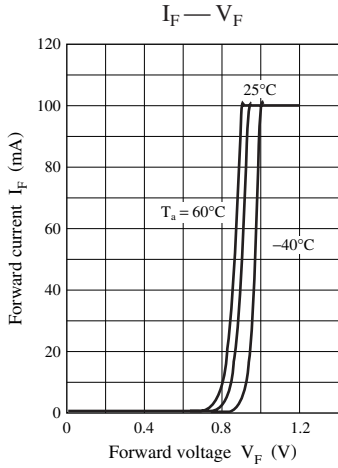
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100 \text{ mA}$		0.92	1.00	V
Reverse current	I_R	$V_R = 33 \text{ V}$		0.01	100.00	nA
Diode capacitance	C_D	$V_R = 6 \text{ V}, f = 1 \text{ MHz}$		0.9	1.2	pF
Forward dynamic resistance *	r_f	$I_F = 2 \text{ mA}, f = 100 \text{ MHz}$		0.65	0.85	Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz.

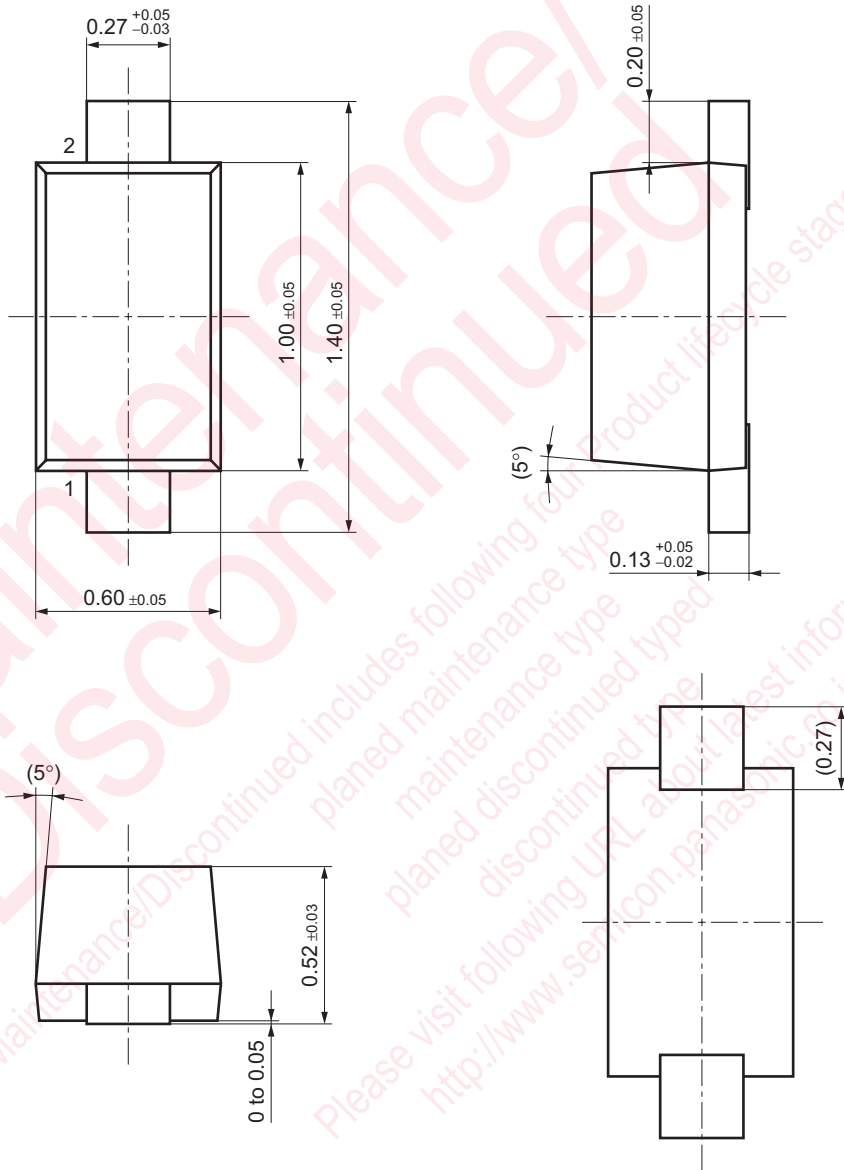
3. *: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER



Maintenance/Discontinued includes following four Product lifecycle state
 planned maintenance type
 maintenance type
 planned discontinued type
 discontinued type
 Please visit following URL about latest information.
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SSSMini2-F3

Unit: mm



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